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Quarterly Reliability Monitoring Results

Quarters: Q3/2021 to Q4/2022

Based on structural similarity

Supplier		User Part Number					
Nexperia B.V. Name of Laboratory Assembly reliability labs		PCMF3USB3S Part Description					
		WLCSP package					
		Test		Test Conditions	Duration	# Lots	# Quantity
	TEST						
	Pre- and Post-Stress						
# 1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below	
		MIL-STD-750-1					
	HTRB	M1038 Method A					
	High Temperature Reverse	Tj = Tjmax, Vr = 100% of max. datasheet					
# 5	Bias	reverse voltage	1000 hours	68	4040	0	
	тс	JESD22-A104					
# 7	Temperature Cycling	-40 °C to 125°C	1000 cycles	24	1440	0	
	UHAST	JESD22-A118					
# 8 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %	– 96 hours				
		JESD22-A102	96 nours	n.a.	n.a.	n.a.	
	AC	Tamb = 121 °C, RH = 100 %					
# 8a	Autoclave	Pressure = 205 kPa (29.7 psia)					
	HAST	JESD22-A110					
	Highly Accelerated Stress	Tamb = 130 °C, RH = 85%, VR = 80 % of					
# 9	Test	rated reverse voltage ^[1]	1000 hours	24	1440	0	
		MIL-STD-750 Method 1037					
	IOL	ton = toff, devices powered to insure $\Delta T j$ =					
# 10	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.	
	RSH	JESD22-A111					
# 20	Resistance to Solder Heat	260 °C ± 5 °C	10 s	n.a.	n.a.	n.a.	
	SD						
# 21	Solderability	J-STD-002		n.a.	n.a.	n.a.	

[1]The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

NXP ICN8 Protection INDI 4040 0 1.1 9.51E+08	Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
	NXP ICN8	Protection INDI	4040	0	1,1	9,51E+08

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